

AMENDMENTS TO THE CLAIMS

Claims 1-8 (**Canceled**)

9. **(Previously Presented)** A printed circuit board comprising:

a substrate having first and second opposite surfaces, a plurality of terminal holes being formed through said substrate from said first surface to said second surface thereof;

an electrically conductive circuit pattern provided on said first surface of said substrate;

wherein said electrically conductive circuit pattern comprises a plurality of composite lands, each of said composite lands including

a first land having a center hole aligned with one of said terminal holes of said substrate so as to allow said center hole and said terminal hole to receive a terminal of an electric or electronic part or device, and

a plurality of second lands each being contiguous to and extending radially outwardly from said first land;

wherein, for each of said composite lands, thermal insulating areas are formed radially outwardly of said first land and circumferentially between adjacent ones of said second lands, each of said thermal insulating areas being constituted by an area of said substrate that is devoid of a conductive layer thereon so as to inhibit thermal conduction away from said first and second lands; and

wherein, for each of said composite lands, a narrow resist layer is formed so as to be arranged along a border between said composite land and each of said thermal insulating areas.

10. **(Previously Presented)** A soldering structure for electric or electronic parts or devices, comprising:

a substrate having first and second opposite surfaces, a plurality of terminal holes being formed through said substrate from said first surface to said second surface thereof;

a first electrically conductive circuit pattern provided on said first surface of said substrate;

a second electrically conductive circuit pattern provided on said second surface of said substrate;

terminal hole conductor layers formed on inner circumferences of said terminal holes, respectively, and electrically connecting said first electrically conductive circuit pattern with said second electrically conductive circuit pattern;

wherein each of said first and second electrically conductive circuit patterns comprises a plurality of composite lands, each of said composite lands including

a first land having a center hole aligned with one of said terminal holes of said substrate so as to allow said center hole and said terminal hole to receive a terminal of one of the electric or electronic parts or devices, and

a plurality of second lands each being contiguous to and extending radially outwardly from said first land;

wherein, for each of said composite lands, thermal insulating areas are formed radially outwardly of said first land and circumferentially between adjacent ones of said second lands, each of said thermal insulating areas being constituted by an area of said substrate that is devoid of a conductive layer thereon so as to inhibit thermal conduction away from said first and second lands; and

wherein, for at least one of said composite lands, a solder lump is formed on said first land for securing the terminal of the respective electric or electronic part or device, said solder lump having a conical shape with said terminal hole being disposed at a center of said conical shape and with outer ribs protruding radially outwardly from said conical shape.

11. **(Previously Presented)** A soldering structure according to claim 10, wherein each of said outer ribs extends from a top to a bottom of said conical shape and, at said bottom, is disposed in one of said thermal insulating areas.

12. **(Previously Presented)** A soldering structure according to claim 10, wherein

for each said solder lump, four of said outer ribs are provided and are spaced circumferentially about said conical shape.

13. **(Previously Presented)** A soldering structure for electric or electronic parts or devices, comprising:

a substrate having first and second opposite surfaces, a plurality of terminal holes being formed through said substrate from said first surface to said second surface thereof;

an electrically conductive circuit pattern provided on said first surface of said substrate; wherein said electrically conductive circuit pattern comprises a plurality of composite lands, each of said composite lands including

a first land having a center hole aligned with one of said terminal holes of said substrate so as to allow said center hole and said terminal hole to receive a terminal of one of the electric or electronic parts or devices, and

a plurality of second lands each being contiguous to and extending radially outwardly from said first land;

wherein, for each of said composite lands, thermal insulating areas are formed radially outwardly of said first land and circumferentially between adjacent ones of said second lands, each of said thermal insulating areas being constituted by an area of said substrate that is devoid of a conductive layer thereon so as to inhibit thermal conduction away from said first and second lands; and

wherein, for at least one of said composite lands, a solder lump is formed on said first land for securing the terminal of the respective electric or electronic part or device, said solder lump having a conical shape with said terminal hole being disposed at a center of said conical shape and with outer ribs protruding radially outwardly from said conical shape.

14. **(Previously Presented)** A soldering structure according to claim 13, wherein each of said outer ribs extends from a top to a bottom of said conical shape and, at said bottom, is disposed in one of said thermal insulating areas.

15. **(Previously Presented)** A soldering structure according to claim 13, wherein for each said solder lump, four of said outer ribs are provided and are spaced circumferentially about said conical shape.